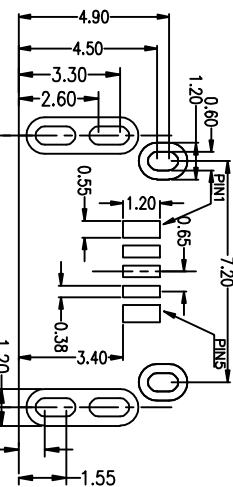
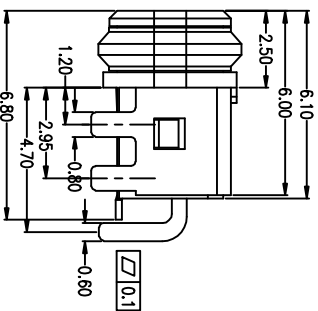
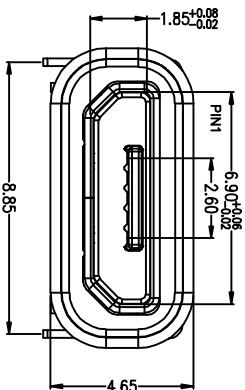
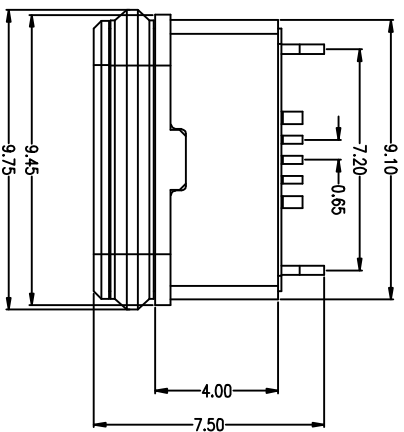
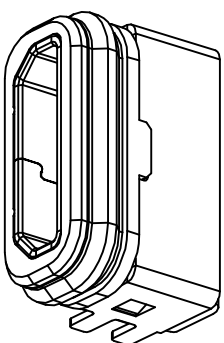
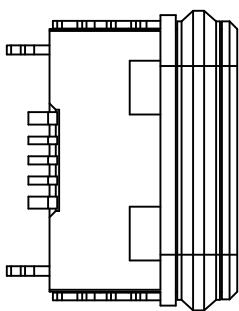
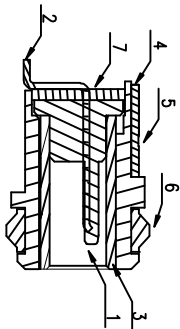


MAPX	MODIFICATION	DATE
------	--------------	------



PCB板层参考

- Note:
- 1.Material:
- 1.1 Housing: High temperature thermoplastic
 - 1.2 Contact: copper alloy,t=0.20mm
 - 1.3 Shell: SUS304,t=0.30mm
 - 1.4 cover: High temperature thermoplastic
 - 1.5 out Shell: SUS304 T=0.25
 - 1.6 Ring: SILICON
 - 1.7 Epoxy: Epoxy
- 2.Specification:
- 2.1 Current rating:1.5PIN 2.0A Max/2.3,4PIN 1A Max.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 30 mΩ Max.
 - 2.4 Insulation resistance: 100 MΩ Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min.
 - 2.7 Temperature range: -30C~80C
 - 2.8 Waterproof: IPX68.



深圳市精拓金电子有限公司

产品图

公称一覽表
PRODUCT GRANT JMG
TOLERANCE UNLESS OTHERWISE

公差	单位	制图	YANG	制图料号	920-A64A2021S101A1
X, ±0.30 X	英寸	审核	郭志富	产品名称	0200 8PIN 连接器 1.5 高脚端子 4.0 间距
.X, ±0.25 .X	比例	日期	2019.11.23	CAD	PRODUCT NO.
.XX, ±0.15 .XX	日期	2019.11.23	核准	美国荣	角法
.XXX, ±0.10 .XXX	日期	2019.11.23	核准	美国荣	版本
					A0